

# SN54BCT623, SN74BCT623 OCTAL BUS TRANSCEIVERS WITH 3-STATE OUTPUTS

SCBS020A – SEPTEMBER 1988 – REVISED NOVEMBER 1993

- State-of-the-Art BiCMOS Design Significantly Reduces  $I_{CCZ}$
- ESD Protection Exceeds 2000 V Per MIL-STD-883C, Method 3015
- Package Options Include Plastic Small-Outline (DW) Packages, Ceramic Chip Carriers (FK) and Flatpacks (W), and Plastic and Ceramic 300-mil DIPs (J, N)

## description

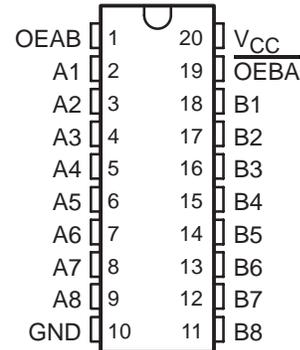
The 'BCT623 bus transceiver is designed for asynchronous communication between data buses. The control function implementation allows for maximum flexibility in timing. The 'BCT623 provides true data at its outputs.

This device allows data transmission from the A bus to the B bus or from the B bus to the A bus depending upon the logic levels at the output-enable (OEAB and  $\overline{OEBA}$ ) inputs.

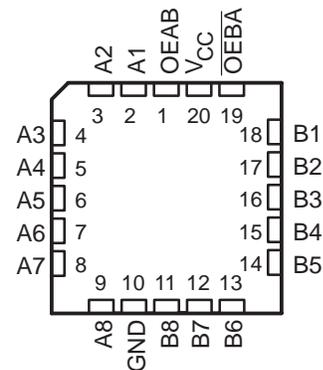
The output-enable inputs can be used to disable the device so that the buses are effectively isolated. The dual-enable configuration gives the transceivers the capability of storing data by simultaneously enabling OEAB and  $\overline{OEBA}$ . Each output reinforces its input in this configuration. When both OEAB and  $\overline{OEBA}$  are enabled and all other data sources to the two sets of bus lines are at high impedance, both sets of bus lines (16 in all) will remain at their last states.

The SN54BCT623 is characterized for operation over the full military temperature range of  $-55^{\circ}\text{C}$  to  $125^{\circ}\text{C}$ . The SN74BCT623 is characterized for operation from  $0^{\circ}\text{C}$  to  $70^{\circ}\text{C}$ .

SN54BCT623 . . . J OR W PACKAGE  
SN74BCT623 . . . DW OR N PACKAGE  
(TOP VIEW)



SN54BCT623 . . . FK PACKAGE  
(TOP VIEW)



FUNCTION TABLE

INPUTS		OPERATION
$\overline{OEBA}$	OEAB	
L	L	B data to A bus
L	H	B data to A bus, A data to B bus
H	L	Isolation
H	H	A data to B bus



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		SN54BCT623		SN74BCT623		UNIT
				MIN	TYP†	MAX	MIN	
$V_{IK}$		$V_{CC} = 4.5\text{ V}$ ,	$I_I = -18\text{ mA}$	-1.2		-1.2		V
$V_{OH}$	A port	$V_{CC} = 4.5\text{ V}$	$I_{OH} = -1\text{ mA}$	2.5	3.4	2.5	3.4	V
			$I_{OH} = -3\text{ mA}$	2.4	3.3	2.4	3.3	
	B port	$V_{CC} = 4.5\text{ V}$	$I_{OH} = -3\text{ mA}$	2.4	3.3	2.4	3.3	
			$I_{OH} = -12\text{ mA}$	2	3.2			
			$I_{OH} = -15\text{ mA}$			2	3.1	
$V_{OL}$	A port	$V_{CC} = 4.5\text{ V}$	$I_{OL} = 20\text{ mA}$	0.3	0.5			V
			$I_{OL} = 24\text{ mA}$			0.35	0.5	
	B port	$V_{CC} = 4.5\text{ V}$	$I_{OL} = 48\text{ mA}$	0.38	0.55			
			$I_{OL} = 64\text{ mA}$			0.42	0.55	
$I_I$	A or B port	$V_{CC} = 5.5\text{ V}$ ,	$V_I = 5.5\text{ V}$	1		1		mA
	OEAB or OEBA			0.1		0.1		
$I_{IH}^\ddagger$	A or B port	$V_{CC} = 5.5\text{ V}$ ,	$V_I = 2.7\text{ V}$	70		70		$\mu\text{A}$
	OEAB or OEBA			20		20		
$I_{IL}^\ddagger$	A or B port	$V_{CC} = 5.5\text{ V}$ ,	$V_I = 0.5\text{ V}$	-0.65		-0.65		mA
	OEAB or OEBA			-0.6		-0.6		
$I_{OS}^\S$	A port	$V_{CC} = 5.5\text{ V}$ ,	$V_O = 0$	-60	-150	-60	-150	mA
	B port			-100	-225	-100	-225	
$I_{CCL}$	A to B	$V_{CC} = 5.5\text{ V}$		58	92	58	92	mA
$I_{CCH}$	A to B	$V_{CC} = 5.5\text{ V}$		33	53	33	53	mA
$I_{CCZ}$		$V_{CC} = 5.5\text{ V}$		6	11	6	11	mA
$C_i$	OEAB or OEBA	$V_{CC} = 5\text{ V}$ ,	$V_I = 2.5\text{ V or }0.5\text{ V}$	5		5		pF
$C_{io}$	A to B	$V_{CC} = 5\text{ V}$ ,	$V_O = 2.5\text{ V or }0.5\text{ V}$	9		9		pF
	B to A			12		12		

† All typical values are at  $V_{CC} = 5\text{ V}$ ,  $T_A = 25^\circ\text{C}$ .

‡ For I/O ports, the parameters  $I_{IH}$  and  $I_{IL}$  include the off-state output current.

§ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.



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## switching characteristics (see Note 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>CC</sub> = 5 V, C <sub>L</sub> = 50 pF, R <sub>1</sub> = 500 Ω, R <sub>2</sub> = 500 Ω, T <sub>A</sub> = 25°C			V <sub>CC</sub> = 4.5 V to 5.5 V, C <sub>L</sub> = 50 pF, R <sub>1</sub> = 500 Ω, R <sub>2</sub> = 500 Ω, T <sub>A</sub> = MIN to MAX†				UNIT
			'BCT623			SN54BCT623		SN74BCT623		
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t <sub>PLH</sub>	A	B	0.5	3.1	4.7	0.5	5.3	0.5	5.2	ns
t <sub>PHL</sub>			1.7	4.9	6.9	1.7	7.6	1.7	7.4	
t <sub>PLH</sub>	B	A	0.9	4.1	5.9	0.9	6.8	0.9	6.7	ns
t <sub>PHL</sub>			1.8	5.3	7.6	1.8	8.3	1.8	8	
t <sub>PZH</sub>	$\overline{\text{OEBA}}$	A	3.1	6.8	9.1	3.1	10.7	3.1	10.6	ns
t <sub>PZL</sub>			3.3	7.2	9.6	3.3	11.3	3.3	10.7	
t <sub>PHZ</sub>	$\overline{\text{OEBA}}$	A	1.9	6.1	8.3	1.9	10.6	1.9	9.8	ns
t <sub>PLZ</sub>			1.1	4.6	7	1.1	8.1	1.1	7.8	
t <sub>PZH</sub>	OEAB	B	2	5	6.8	2	7.8	2	7.6	ns
t <sub>PZL</sub>			2.7	6.2	8	2.7	9.3	2.7	8.9	
t <sub>PHZ</sub>	OEAB	B	1.1	4.6	6.5	1.1	8	1.1	7.7	ns
t <sub>PLZ</sub>			0.3	3.2	6.3	0.3	7.2	0.3	7.1	

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.



**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
5962-9094001MRA	ACTIVE	CDIP	J	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9094001MR A SNJ54BCT623J	
SNJ54BCT623J	ACTIVE	CDIP	J	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9094001MR A SNJ54BCT623J	

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "-" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

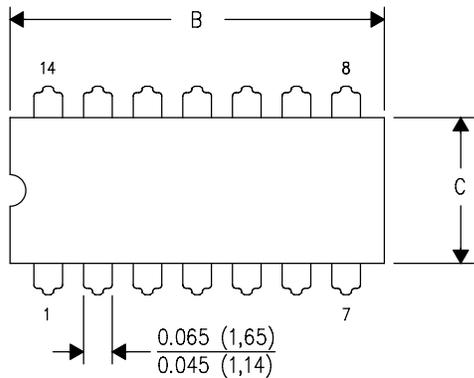
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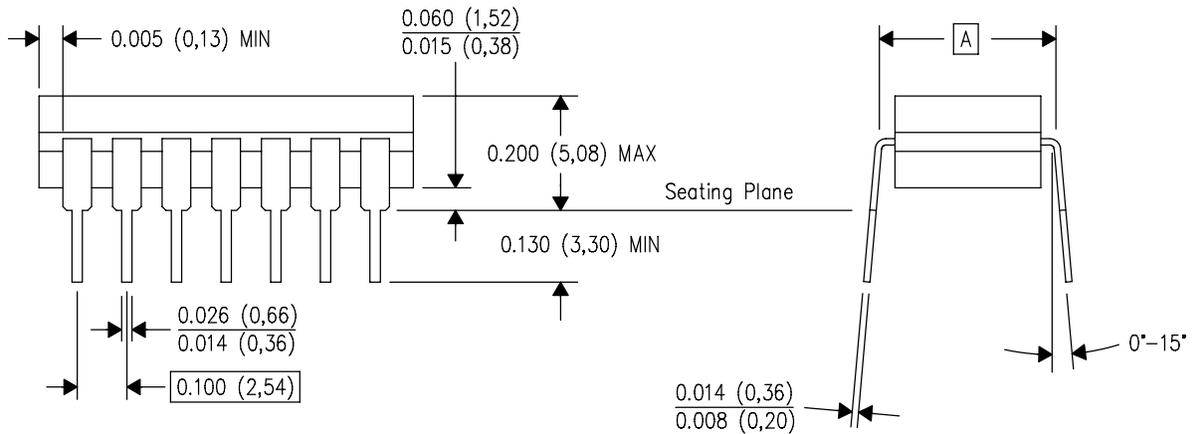
J (R-GDIP-T\*\*)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package is hermetically sealed with a ceramic lid using glass frit.
  - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
  - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

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